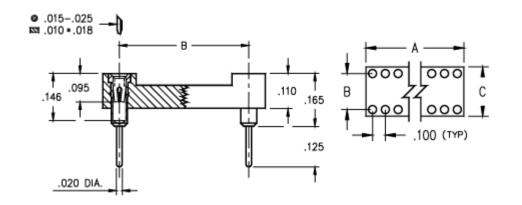


DATA SHEET

Product Number: 110-93-316-41-001100



Description:

DIP Socket Solder Tail Standard Solder Tail (0.125 Tail) Open Frame Through Hole Accepts .015-.025" Leads

Plating Code: 93

Shell Plating:

200 μ" Tin/Lead(93/7) over 100 μ" Nickel

Inner Contact Plating: 30 μ" Gold over 50 μ" Nickel

Packaging:

Packaged in Tubes

# Of Pins	A	В	С	Qty. per Tube	Mill-Max Part Number	RoHS Compliant
16	0.8	0.3	0.4	25	110-93-316-41-001100	NO

CONTACT:

Contact Used: #30, Standard 4 Finger Contact

Current Rating = 3 Amps

BERYLLIUM COPPER ALLOY 172 (UNS C17200) per **ASTM B 194**

Properties of BERYLLIUM COPPER:

Chemical composition: Cu 98.1%, Be 1.9%

Temper as stamped: TD01

Properties after heat treatment (TH01):

• Hardness: 36-43 Rockwell C Mechanical Life: 100 Cycles Min.

Density: .298 lbs/in3

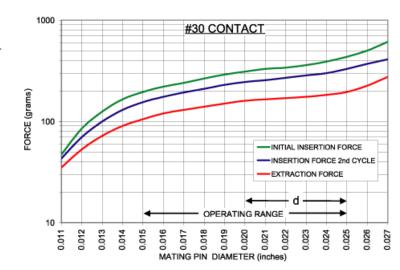
Electrical Conductivity: 22% IACS*

Resistance: 10 miliohms Max

Operating Temperature: -55°C/+125°C

Melting point: 980°C/865°C (liquidus/solidus)

Stress Relaxation†: 96% of stress remains after 1,000 hours @ 100 °C; 70% of stress remains after 1,000 hours @ 200 ٥C



†Since BeCu loses its spring properties over time at high temperatures; it is rated for continuous use up to 150°C. For applications up to 300°C, Mill-Max offers many contacts in Beryllium Nickel. Contact Tech Support for more info.

^{*}International Annealed Copper Standard, i.e. as a % of pure copper.

LOOSE PIN:

Loose Pin Used: 1001

BRASS ALLOY (UNS C36000) per ASTM B 16

Properties of BRASS ALLOY:

• Chemical composition: Cu 61.5%, Zn 35.4%, Pb 3.1%†

• Hardness as machined: 80-90 Rockwell B

• Density: .307 lbs/in3

• Electrical conductivity: 26% IACS*

• Melting point: 900°C/885°C (liquidus/solidus)

†(3 to 4% lead is used to permit "free machining" and is permitted by EC Directive 2002/95Annex 6; so all pin materials are RoHS compliant)

INSULATOR INFORMATION:

PCT Polyester, (Thermx CG933, black)

High Temperature

Properties of PCT Polyester:

Brand: ThermxGrade: CG-933

• Rated voltage: 100 VRMS/150 VDC

• Insulation resistance: 10,000 Megaohms min.

• Material Heat Deflection Temp (per ASTM D 648): 529°F (276°C) @ 66 psi

• Dielectric strength: 1000 VRMS min. (700 VRMS min. for series 117 Shrink DIP)

Note: Materials above 446°F (230°C) are considered suitable for "eutectic" reflow soldering, above 500°F (260°C) for "lead-free" reflow soldering.

^{*}International Annealed Copper Standard, i.e. as a % of pure copper.